

Application No.: 10/534,251Docket No.: 4590-397**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (currently amended): An electronic component mounted in an individual package and intended to be connected to other components of an electronic system, said electronic component comprising:

[[an]] one or more integrated circuit ~~chip~~ chips working around a main millimetric frequency F greater than 45 GHz, wherein said package has at least two ports for communicating electrical signals between the interior and the exterior of said package, the first port being a port with transition by contactless electromagnetic coupling for the transmission of signals at the main working frequency greater than 45 GHz, and the second port being a port with microstrip or coaxial type transition for the transmission of a working frequency F/N that is a subharmonic of the main frequency F where N is ≥ 2 .

2. (currently amended): The component as claimed in claim 1, wherein the package is provided with a conductive cover positioned at a distance from the first port such that [[it]] said conductive cover sets up, above this port, an electromagnetic short circuit at the main working frequency, thus forming a wave reflector facilitating the transmission of this frequency through the first port.

3. (previously presented): The component as claimed in claim 2, wherein the conductive cover is at a height above the port equal to a quarter of the wavelength, or an odd multiple of the quarter of the wavelength of the working frequency.

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4. (previously presented): The component as claimed in claim 1, wherein one of the chips included in said package comprises means of multiplying frequency in a ratio N to change from the subharmonic frequency to the main working frequency.

5. (currently amended): The component as claimed in claim 1, ~~wherein it~~ comprising a ceramic substrate, a first metallized side of which is etched to form a microstrip line having a free end and another side of which is also metallized to form a ground plane, the ground plane being interrupted facing the free end, to provide contactless electromagnetic coupling between the ~~outside~~ interior and the ~~inside~~ exterior of the package via the microstrip line free end.

6. (currently amended): The component as claimed in claim 5, wherein ~~[[the]]~~ a conductive cover is at a height above the free end of the microstrip line equal to a quarter of the wavelength, or an odd multiple of a quarter of the wavelength of the working frequency.

7. (currently amended): The component as claimed in claim 5, ~~wherein it includes~~ comprising a metallic base open facing the microstrip ~~line~~ free end.

8. (currently amended): The component as claimed in claim 1, ~~wherein it includes~~ comprising one or more MMIC chips fixed on a base, one of the chips including a microstrip line, of which one free end is used as a contactless electromagnetic transition, ~~[[this]]~~ said one chip extending over an opening in the base so that the free end of the line is located in line with the opening, in order to form a contactless electromagnetic transition through this opening.

9. (previously presented): The component as claimed in claim 2, wherein one of the chips included in said package comprises means of multiplying frequency in a ratio N to change from the subharmonic frequency to the main working frequency.

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10. (previously presented): The component as claimed in claim 3, wherein one of the chips included in said package comprises means of multiplying frequency in a ratio N to change from the subharmonic frequency to the main working frequency.

11. (currently amended): The component as claimed in claim 2, ~~wherein it~~ comprising a ceramic substrate, a first metallized side of which is etched to form a microstrip line having a free end and another side of which is also metallized to form a ground plane, the ground plane being interrupted facing the free end, to provide contactless electromagnetic coupling between the ~~outside~~ interior and the ~~inside~~ exterior of the package via the microstrip line free end.

12. (currently amended): The component as claimed in claim 3, ~~wherein it~~ comprising a ceramic substrate, a first metallized side of which is etched to form a microstrip line having a free end and another side of which is also metallized to form a ground plane, the ground plane being interrupted facing the free end, to provide contactless electromagnetic coupling between the ~~outside~~ interior and the ~~inside~~ exterior of the package via the microstrip line free end.

13. (currently amended): The component as claimed in claim 4, ~~wherein it~~ comprising a ceramic substrate, a first metallized side of which is etched to form a microstrip line having a free end and another side of which is also metallized to form a ground plane, the ground plane being interrupted facing the free end, to provide contactless electromagnetic coupling between the ~~outside~~ interior and the ~~inside~~ exterior of the package via the microstrip line free end.

14. (currently amended): The component as claimed in claim 6, ~~wherein it includes~~ including a metallic base open facing the microstrip ~~line~~ free end.

15. (currently amended): The component as claimed in claim 2, ~~wherein it includes~~ including one or more MMIC chips fixed on a base, one of the chips including a microstrip line, of which one free end is used as a contactless electromagnetic transition, ~~this chip~~ said one extending over an opening in the base so that the free end of the line is located in line with the opening, in order to form a contactless electromagnetic transition through this opening.

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16. (currently amended): The component as claimed in claim 3, ~~wherein it includes~~ including one or more MMIC chips fixed on a base, said one of the chips including a microstrip line, of which one free end is used as a contactless electromagnetic transition, this chip extending over an opening in the base so that the free end of the line is located in line with the opening, in order to form a contactless electromagnetic transition through this opening.

17. (currently amended): The component as claimed in claim 4, ~~wherein it includes~~ including one or more MMIC chips fixed on a base, said one of the chips including a microstrip line, of which one free end is used as a contactless electromagnetic transition, this chip extending over an opening in the base so that the free end of the line is located in line with the opening, in order to form a contactless electromagnetic transition through this opening.